

## **Amendments to the Specification**

Please replace the paragraph beginning on page 25, line 23, with the following rewritten paragraph.

Additional inspection systems that may be used to perform the methods described herein are illustrated in U.S. Patent Application Serial No. ~~\_\_\_/\_\_\_,\_\_\_~~10/456,203 entitled "Systems for Inspection of Patterned or Unpatterned Wafers and Other Specimen" by Bevis et al. filed June 6, 2003, which is incorporated by reference as if fully set forth herein. The inspection systems described herein may be further configured as described in this patent application.